

Oak Hill Probe to KLM Probe Transfer 1M76G - Lance Correlation



19/05/2011, Sirajul Fahmi / Douglas Garrett

0. Introduction – Reason for Probe Site Qualification

- ✓ **NPI Site to Mass Production Site** - Expected (normal) product transfer from NPI (Fab) Probe Site to Mass Production Site. This transfer minimizes logistical complexities and offers flexibility and synergy between Probe and Final Test.

1. Objective and Considerations

1.1 Objective

- Objective is to qualify KLM Probe facility as joint probe site for probing 1M76G Lance. Complete list of affected parts is outlined in PCN QSD.
- Scheduled to complete by 06/15/2011
- (No) impact of customer deliveries

1.2 Considerations

- Test Platform Hardware in KLM Probe is identical platform used in OHP Probe, and verified by tester calibration and dual site Kappa comparative analysis (see slide).
- Identical probe card design used in both sites
- Test Program Revision and test limits are identical in both sites.
- Measurement Systems Analysis (GR&R) performed per 12MRM97179A proving bin / yield repeatability.
- Visual Inspection including Bond Pads per global specification 12M54564J

2. Correlation Plan

2.1 Pre-Correlation items

- Installed and Verified:
 - Navigator setup and control map files
 - Tester config requirements (hardware/operating system version)
 - Probe card documents (PRVX, Schematic, Drawing)
 - Prober files (xx e.g. TEL-P8XL probe)
 - PROMIS flow (see slide)
 - All Bin monitoring systems and limit files
 - Zero Defect files (EWM, DPAT, and GDBC Files)
- Verified installation and lock-down of W81M76G test program version A03_B07C (Logic), version B07_001 (UTI).
- Probe Card Repair completed incoming inspection on probe card

2. Correlation Plan

2.2 OHP vs. KLM Correlation Plan

Probe Correlation:

- Completed hardware correlation
- 6 wafers (2 wafers from 3 separate wafer lots) / 3 Probe Cards
- Confirmed cross-site correlation on all 6 wafers on yield distribution

3. Correlation Criteria

3.1 Correlation Criteria

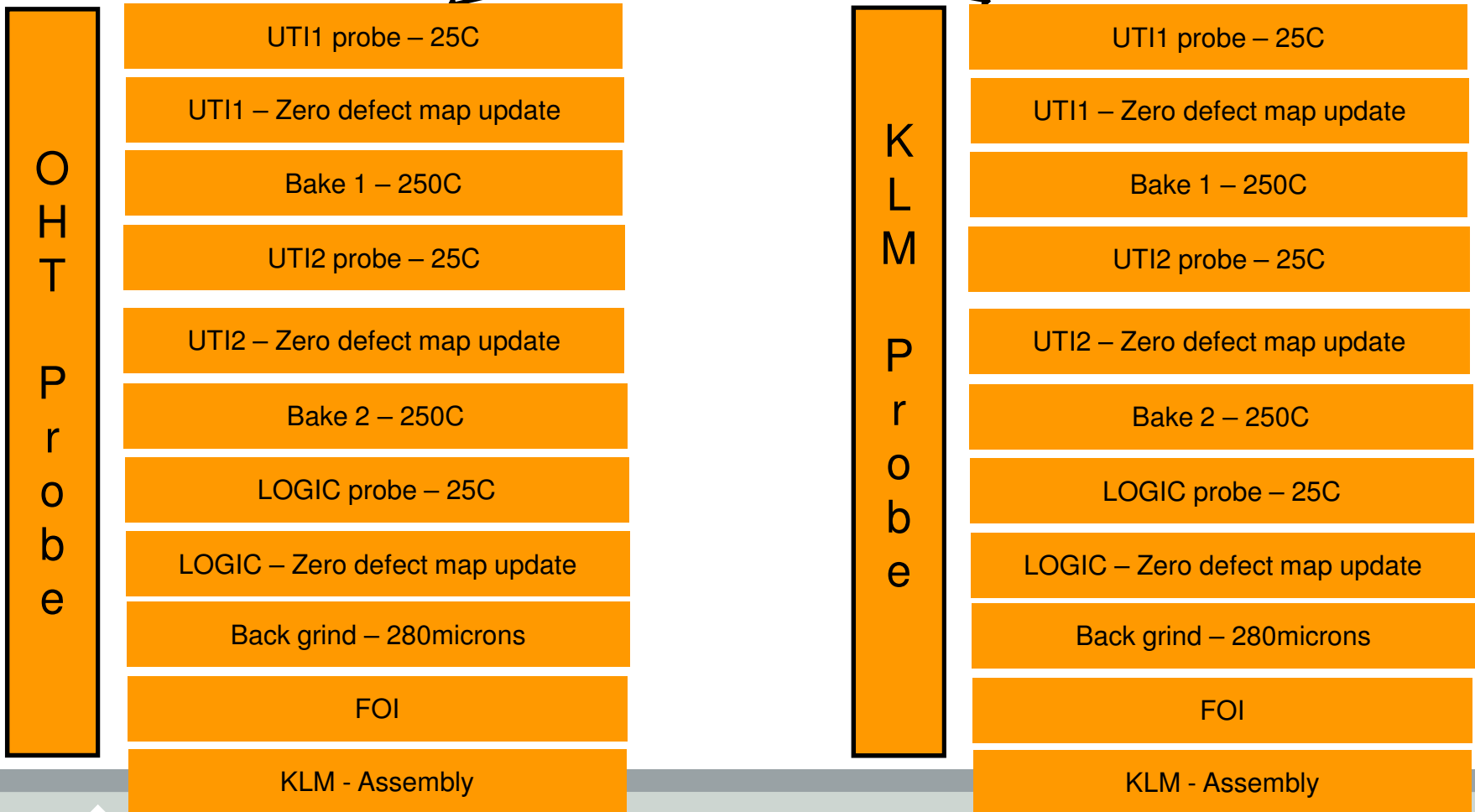
(According to Global Probe Transfer Specification 12MQS10020G)

Yield & Bin Correlation

- Fully probe (test) all six wafers (2 wafers from 3 separate wafer lots) in OHP Probe
- Fully probe (test) the same six correlation wafers in KLM Probe
 - Bin variation must pass within 6%
 - Yield variation must pass within 3%

4. Probe Flow Comparison (Promis Probe Flow comparison)

Exchanging pre-correlation items
(section 2.1)



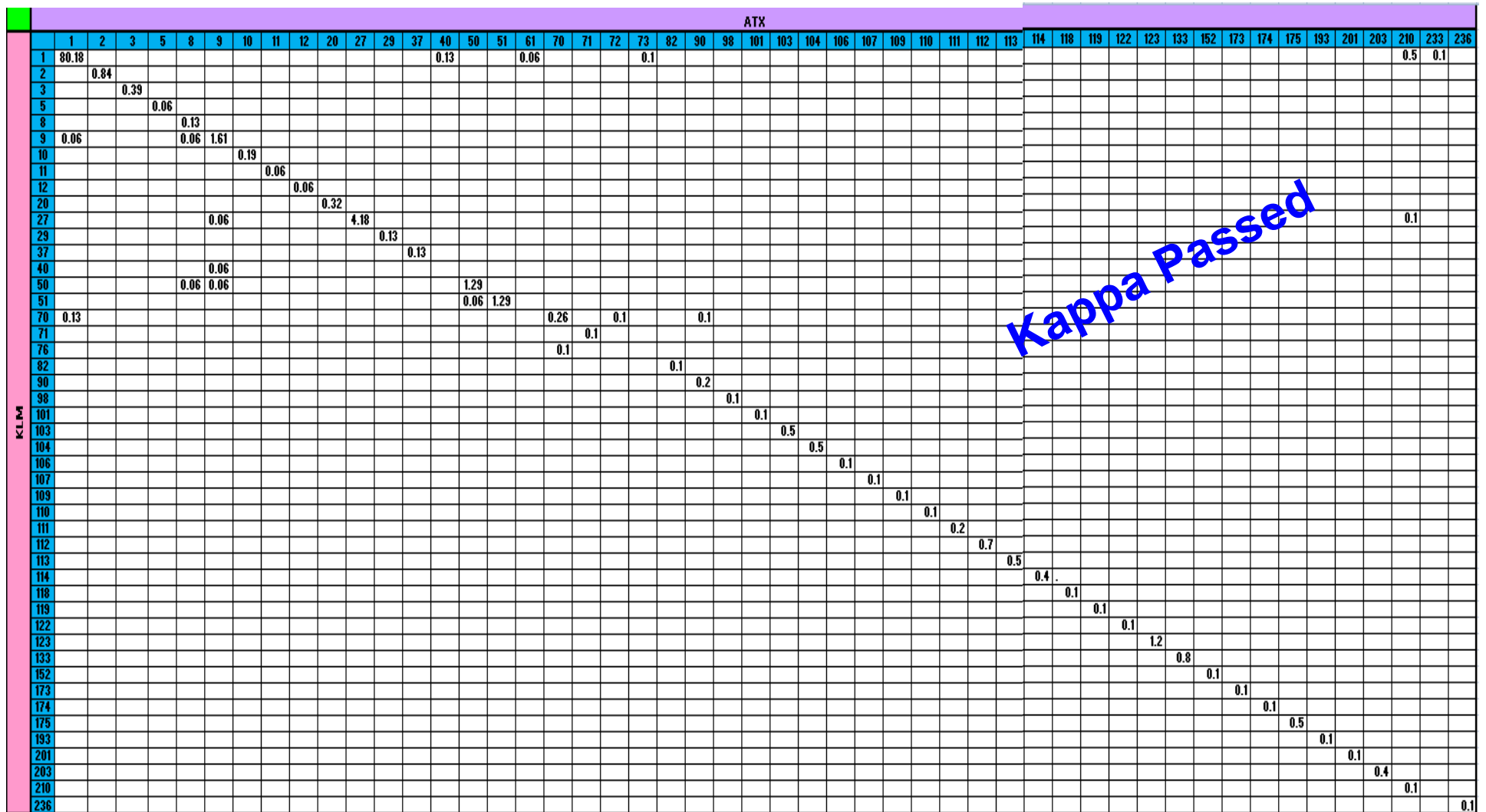
5. Bin to Bin Variation – Overall UTI Results

	ATX																	
	2	55	100	103	104	106	110	111	112	113	117	118	119	123	127	132	133	151
KLM	2	2.32																
	55		91.06			0.13							0.06	0.13				
	100			0.77	0.06													
	103				0.51				0.06					0.06				
	104					0.19												
	106						0.06											
	109		0.06															
	110						0.06											
	111							0.26										
	112		0.06						0.64									
	113									0.26								
	114		0.32														0.06	
	117					0.06												
	118					0.06						0.06						
	119												0.06					
	123		0.13						0.06		0.06			0.71			0.06	
	127														0.06	0.06		
	132															0.06		
	133																0.901	
	151																	0.064
	152		0.193															
	158										0.064							
	162		0.129															

Kappa Passed

*All data in percentage %

5. Bin to Bin Variation – Overall Logic Results



*All data in percentage %

6. Correlation Summary

Kappa Assessment

UTI Result				
Wafer#	2	3	4	Overall
Bin Kappa Correlation Error Mean(<6.0%)	1.73%	2.50%	1.54%	1.93%
Yield kappa Correlation Error Mean (<3.0%)	1.06%	1.24%	1.11%	1.13%
LOGIC Result				
Wafer#	5	6	7	Overall
Bin Kappa Correlation Error Mean(<6.0%)	1.35%	1.35%	2.70%	1.80%
Yield kappa Correlation Error Mean (<3.0%)	0.76%	0.38%	1.90%	1.01%

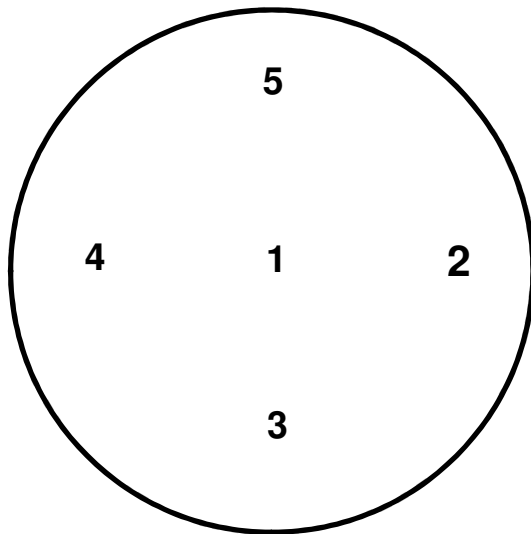
PASSED

PASSED

- Kappa wafer analysis showed that the yield from both Probe sites are not statistically different in yield. Bin fallout from both sites were also comparable.

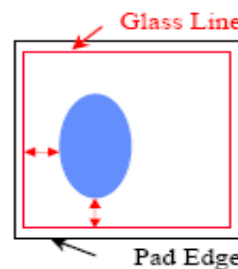
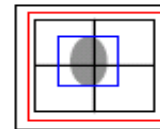
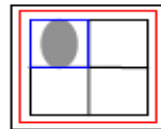
7. Probe Mark Inspection

- Criteria: Probe mark must be > than 5 microns from the passivation opening (Glass Line) per specification 12MTX10001G



Probe Mark Inspection Points

	Min Distance From Edge (microns)
Point 1	19
Point 2	21
Point 3	23
Point 4	18
Point 5	22



PASS

8. Interlayer Dielectric Study

Wafers:

KLM W81M76G

- DD85622 wafer 1

Probe Card:

Single dut x1 (Cantilever type)

Card: 75M76G0104

Platform:

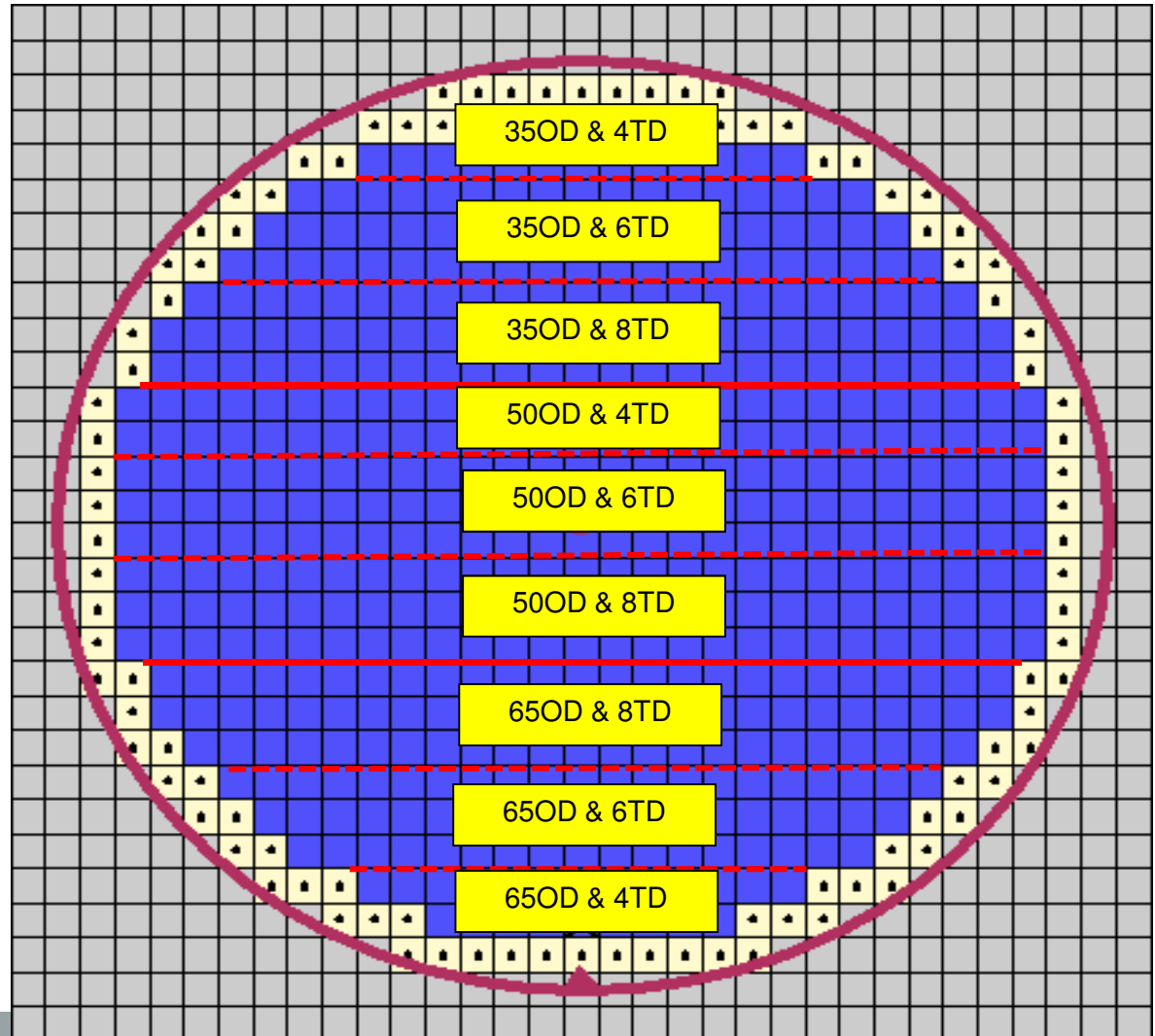
Teradyne J750 / TEL P8XL

KLM system KLJ750-28

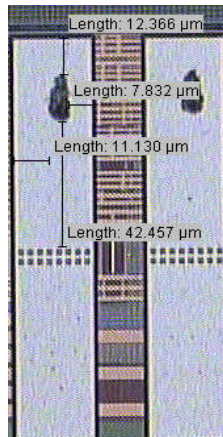
Inputs:

- 3 overdrives
 - 50 - Nominal
 - 35
 - 65
- 3 levels of probe events (Touch downs, TD)
 - 4 TD
 - 6 TD
 - 8 TD
- ZPTPA at -10
- measured planarity = 20-25µm
- Double touch probe
- Room temp probe (25C)

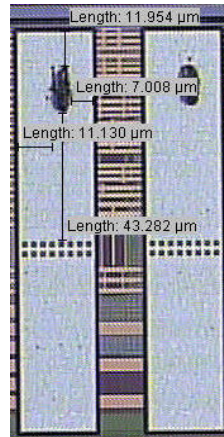
Note: ILD study is a destructive test that removes the aluminum bond pad to check for punctures or cracks in the ILD.



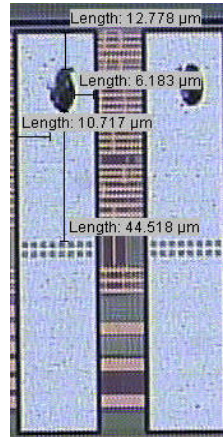
8.1 Interlayer Dielectric Results



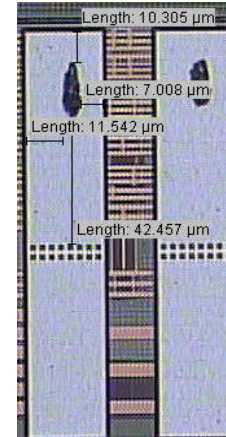
35um at 4TD



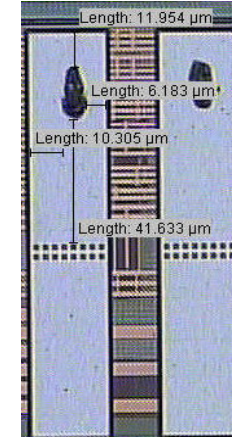
35um at 6TD



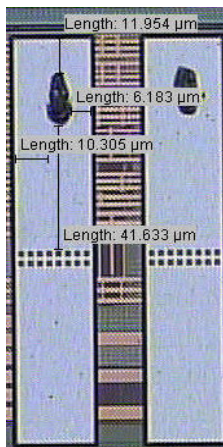
35um at 8TD



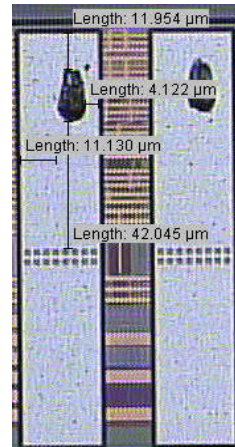
50um at 4TD



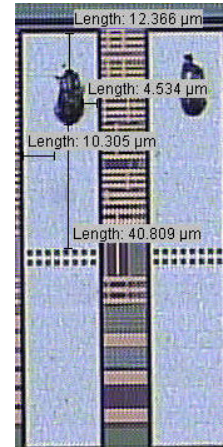
50um at 6TD



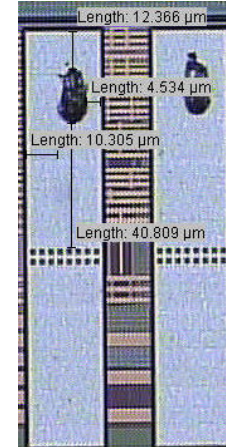
50um at 8TD



65um at 4TD

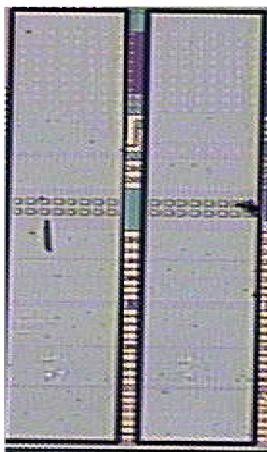


65um at 6TD

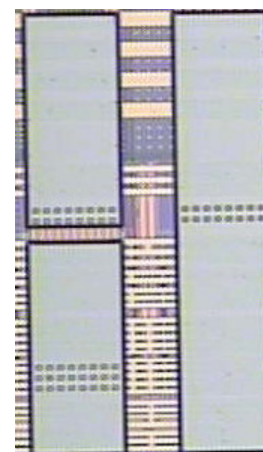


65um at 8TD

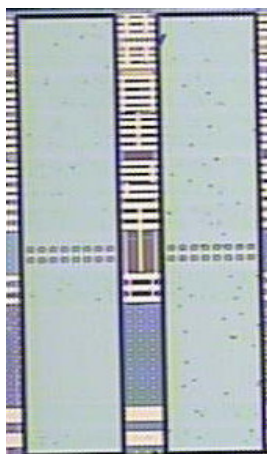
8.1 Interlayer Dielectric Results



65um at 6TD

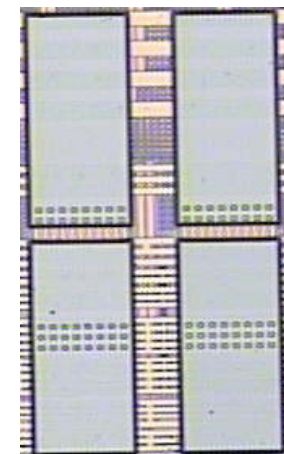


50um at 6TD



65um at 8TD

Note: With visual
Inspection No Dimples
or Cracks were seen.



50um at 8TD

8.1 Interlayer Dielectric Results

M76G Probe ILD Inspection

Probe site: KLM

13-Jun-11

Inspected by Sirajul Fahmi

Test Platform	Probe Stresses		ILD Inspection Results	
	Overdrive	Probe Events	Die Inspected	% Failed (wafer#1)
Teradyne J750	35	4	100% dies	0%
		6	100% dies	0%
		8	100% dies	0%
	50	4	100% dies	0%
		6	100% dies	0%
		8	100% dies	0%
	65	4	100% dies	0%
		6	100% dies	0%
		8	100% dies	0%

100% pads inspected per die.

Pad failure rate reported in percentage of probed pads affected

9. Conclusion and Recommendation

9.1 Conclusion

- Based on this report, 1M76G passed all Probe correlation requirements according to FSL rules without any issues.

9.2 Recommendation

- Test program for 1M76G can be released in KLM Probe
- Track probe and final test yields to check for equivalence on lead production lots.

